ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and	mposition De 05. IPC, Bannockt d Pan-American co	c laration ourn, Illinois. A opyright conve	All rights reserved un ntions.	nder both	This docume level parts, th	ent is a declaration en	n of the substand compasses all lo	es within the manu wer level materials	facturer listed for which the	d item. Note: if e manufacturer	the item is an as has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form ' http://www.ipc.org/IPC-175x Distribution								Aaterials and	tials and Mfg Information			
upplier Information													
ompany name*	Company unique ID			ι	Unique ID Authority				Response Date*				
nsemi									2024-04-25				
Contact Name Title			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			Phone - Representative*			Emai	Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	FCPF85	FCPF850N80Z SF2 800V 850		nOhm E TO220F		2024-04-25		CNP		2107.333	mg	Each	
Ianufacturing Proccess Infor	mation												
Terminal Plating / Grid Arra	Terminal Plating / Grid Array Material Terminal Ba		e Alloy J-STD-020 MSL R		Rating	Peak Process Body Temperatur		ture Max Time at	Peak Tempe	rature Numbe	er of Reflow Cyc	cles	
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0 C 30		30	sec	onds 3			
omments													
or more information regarding mate	erial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	13.5	mg	Supplier	Silicon (Si)	7440-21-3		13.5	mg
Die Attach	4.013	mg	Supplier	Silver (Ag)	7440-22-4		0.0602	mg
			А	Lead (Pb)	7439-92-1	7a	3.7522	mg
			Supplier	Tin (Sn)	7440-31-5		0.2007	mg
Lead Frame	1289.5	mg	Supplier	Silver (Ag)	7440-22-4		2.579	mg
			Supplier	Iron (Fe)	7439-89-6		1.2895	mg
			Supplier	Copper (Cu)	7440-50-8		1285.2446	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3868	mg
Mold Compound	785.0	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		23.55	mg
			Supplier	Proprietary	Proprietary Data		11.775	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		39.25	mg
			Supplier	Carbon Black (C)	1333-86-4		3.925	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		117.75	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		39.25	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		549.5	mg
Plating	13.2	mg	Supplier	Tin (Sn)	7440-31-5		13.2	mg
Wire Bond - Al	2.12	mg	Supplier	Aluminum (Al)	7429-90-5		2.12	mg